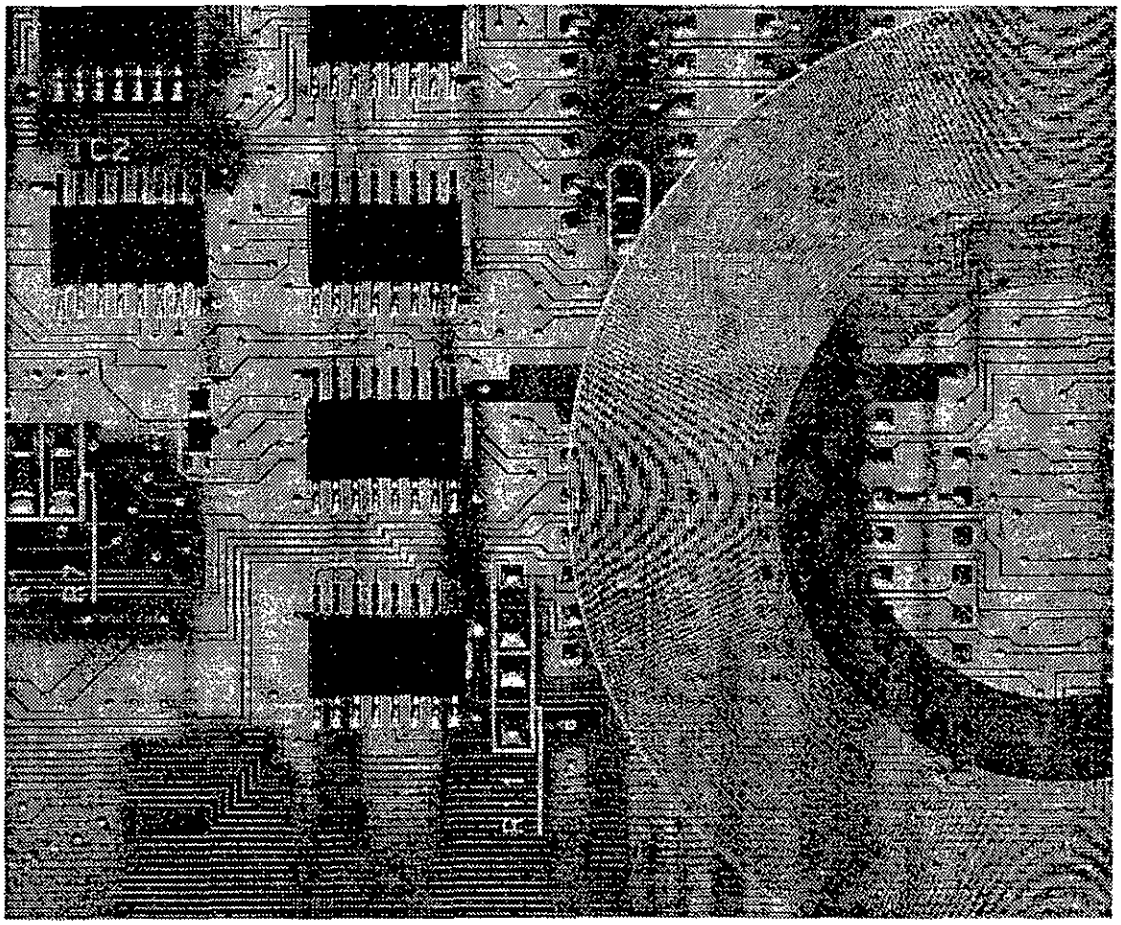
NITTO DENKO
PRODUCT INFORMATION

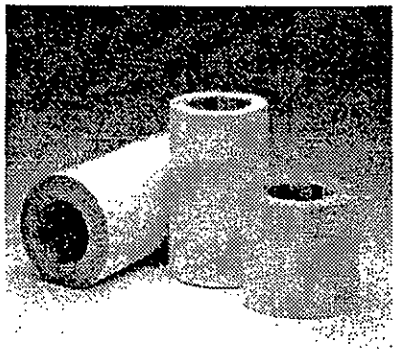
Ref. No.
DC5911 – D03 – E 11/90

High Heat – resistant and High Purity

NITTO DOUBLE – COATED ADHESIVE TAPE NO.5911



No.5911 provides high reliability in the electronics industry.



The recent remarkable advance of the elctronics industry in Japan demands very high grade double – coated tapes featured by upgraded functions such as high holding force, high heat resistance, high purity and high chemical resistance. NITTO DENKO has developed a novelty double – coated tape, **No.5911**, consisting of only NITTO's original acrylic – based adhesive. It withstands well the reflow soldering process due to its high heat resistance and seldom generates volatile matter which often caused troubles. This is ideal for use in the clean environment necessary for the electronics industry.

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1. Features

1) Excellent Adhesive Strength at High Temperatures

No.5911 shows excellent adhesive strength and holding strength at high temperature. It also gives high initial adhesion in the normal temperature range.

2) Excellent Chemical Inertness

The tape can be used in the chemical cleaning process; the holding strength is seldom deteriorated even after immersion in toluene, methyl ethyl ketone, alcohol, etc.

3) High Purity Adhesive

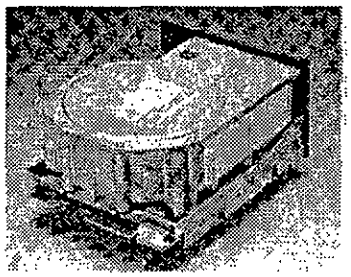
The tape generates little gas at high temperature, so, it gives no adverse effect on the surroundings. Accordingly, it is ideal for use in the clean environment necessary for the electronics industry.

4) Available for Fine Processing

The tape shows excellent punchability and makes little adhesive oozing.

2. Application

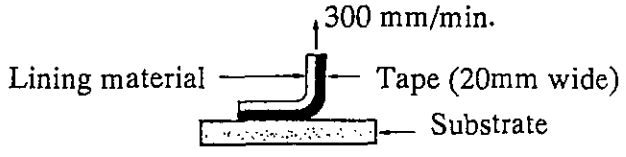
For fine bonding of electronic components and equipment (fixing packing of closed type electronic equipment, fixing circuit peripheral components, etc.)



3. General Properties

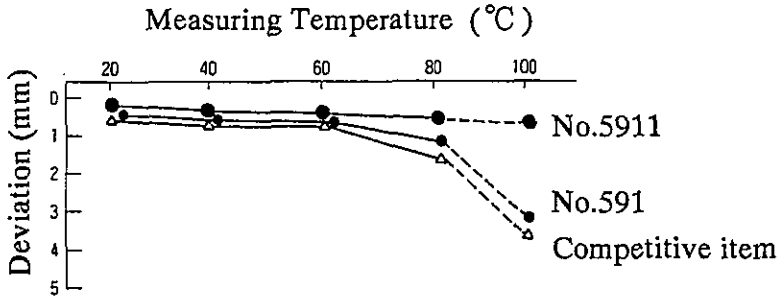
			No.5911		No.591	Competitive Item
Adhesive layer thickness			0.03	0.05	0.05	0.04
Backing			None			
Property	Lining material	Substrate				
90° peel strength (g/20mm)	Polyimide	Bakelite	1650	2510	1660	1490
	Copper foil		1450	1800	1640	1280

Test method

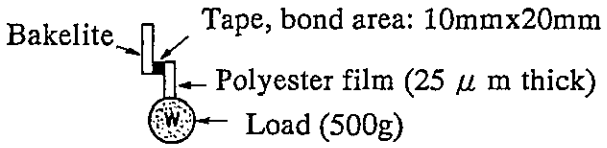


4. Heat Resistance

Holding Strength vs. Temperature

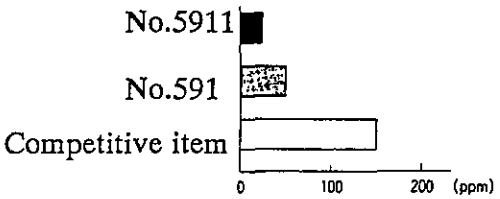


Testing method



5. Purity

Volatilization from the Tape



Testing method

Analyzed by gas chromatography.

6. Standard Sizes

Thickness (mm)		Width (mm)	Length (m)
Adhesive layer	Release paper		
0.03	0.12	450	50
0.05			

For other sizes, please contact us.

NOTE: Techinical data figures herein presented are typical and should not be used for any specification purposes.